




**Gas Discharge Tube
Features**

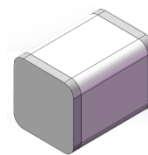
- Small Size Design 4.5×3.2×3.2mm Current
- Handling Capability 2,000A @ 8/20μ s
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level: Level 1

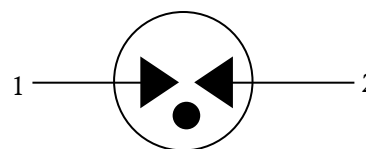
Application information

- AC Power

Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	Compliance with UL1449, Certificated E337906
	NO.B 104564 0001 Rev.00

Exterior

SMD
Package (Top View)

Schematic Symbol


DC Breakdown Voltage 1)2)	100V/s	3600(-20%~+20%)	V
Impulse Spark-over Voltage	At 1KV/μs	For 99% of measured values ≤4800	V
	At 1KV/μs	Typical values of distribution ≤4700	V
Hi-pot Test	I _D =10mA	≥1800	V
Impulse Discharge Current 3)	8/20μs ± 5times	2,000	A
Impulse Discharge Current 3)	1.2/50μs ± 40Times	10kV/12Ω	A
Impulse Discharge Current 3)	10/1000μs ± 5Times	10	A
AC Discharge Current	2A1S	1	Time
Arc Voltage	At 1A	~15	V
Insulation Resistance	DC=100V	≥1	GΩ
Capacitance at 1 MHz	V _{DC} =0.5V	≤1	pF
Weight		~0.25	g
Operating And Storage Temperature		-40-125	°C
Marking		Without	

1) At delivery AQL 0.65 level II ISO 2859

2) In ionized mode

3) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Gas Discharge Tube

Version: A3 2019-09-25

Part Numbering System

BC 3600

(1) (2)

(1) Bencent Gas Discharge Tube

(2) Series: DC Breakdown Voltage, e.g.: 3600=3600V

Product Characteristics

Lead Material	Copper or iron nickel alloy
Body Material	Ceramics
Terminal Finish	100% Matte-Tin Plated

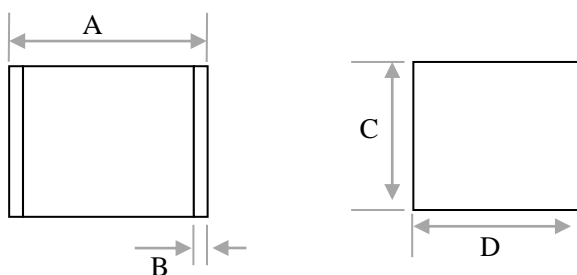
Environmental Reliability Characteristics

Testing items	Technical standards
High Temperature Storage Test	Temperature: 125°C Time: 2H
Low Temperature Storage Test	Temperature: -40°C Time: 2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45mins
Resistance of soldering heat	Temperature: 260±5°C Time of dip soldering: 10s, 1time

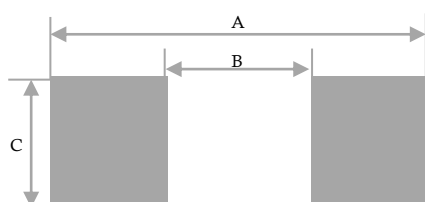
Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability test

Solderability	Solder Pot Temperature:	245°C ± 5°C
	Solder Dwell Time:	4-6 seconds

Product Dimensions


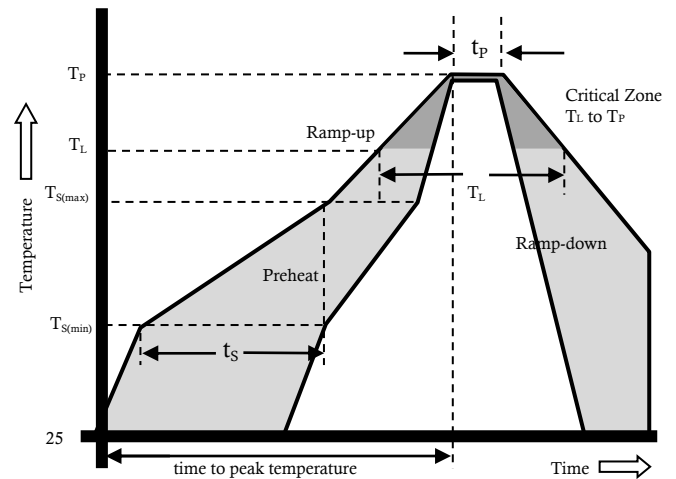
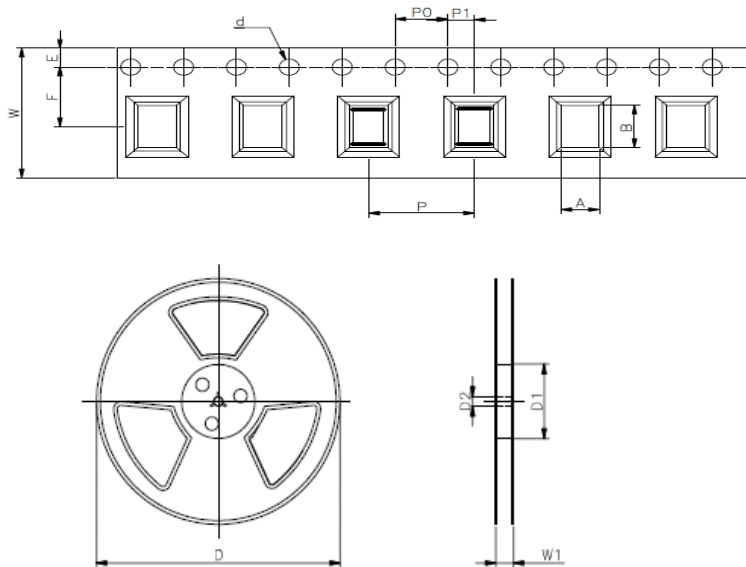
REF	mm	inch
A	4.5±0.3	0.177±0.012
B	0.45±0.2	0.018±0.008
C	3.2±0.2	0.126±0.008
D	3.2±0.2	0.126±0.008

Recommended Soldering Pad


REF	mm	inch
A	4.8	0.189
B	3.3	0.130
C	3.5	0.138

Reflow Profile

Reflow Condition		Pb-Free assembly
Pre Heat	Temperature Min	150 °C
	Temperature Max	200 °C
	Time (min to max)	60 – 180 secs
Average ramp up rate (Liquids) T _{amp} (T _L) to peak		3 °C/second max
T _S (max) to T _L - Ramp-up Rate		3 °C/second max
Reflow	- Temperature (T _L) (Liquids)	217 °C
	- Temperature (T _L)	60 – 150 seconds
Peak Temperature (T _P)		260+0/-5 °C
Time within 5 °C of actual peak Temperature (t _p)		8 – 20 seconds
Ramp-down Rate		6 °C/second max
Time 25 °C to peak Temperature (T _P)		8 minutes Max.
Do not exceed		260 °C


Package Reel Information


REF	mm	inch
A	3.7±0.2	0.146±0.008
B	5.0±0.1	0.197±0.004
d	Φ 1.5±0.1	Φ 0.059±0.004
E	1.75±0.1	0.069±0.004
F	5.5±0.1	0.217±0.002
P	8.0±0.1	0.315±0.004
P0	4.0±0.1	0.157±0.004
P1	2.0±0.1	0.079±0.004
W	12.0±0.2	0.472±0.008
D	Φ330.0	Φ13.0
D1	Φ50Min	Φ1.97Min
D2	Φ13±0.5	0.512±0.02
W1	16.8±2.0	0.661±0.079

OUTLINE	REEL (PCS)	PER CARTON (PCS)	REEL DIAMETERS (mm)	CARTON SIZE(mm)		
				L	W	H
TAPING	2,500	40,000	330	360	360	380